



Material Content Data Sheet



Sales Product Name		TLE42994E V33		Issued		26. September 2017			
MA#		MA000970130							
Package		PG-SSOP-14-2		Weight*		83.48 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.995	3.59	3.59	35880	35880	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103		
		non noble metal	zinc	7440-66-6	0.034	0.04		413	
		non noble metal	iron	7439-89-6	0.689	0.83		8254	
wire	noble metal	non noble metal	copper	7440-50-8	27.978	33.51	34.39	335129	343899
		noble metal	gold	7440-57-5	0.153	0.18	0.18	1830	1830
		organic material	carbon black	1333-86-4	0.097	0.12		1159	
encapsulation	plastics	epoxy resin	-	4.451	5.33		53312		
		inorganic material	silicondioxide	60676-86-0	43.830	52.50	57.95	525010	579481
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11692	11692	
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9195	9195	
glue	plastics	epoxy resin	-	0.376	0.45		4506		
		noble metal	silver	7440-22-4	1.128	1.35	1.80	13517	18023
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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